



# GR4MBF

## Surface Mount Fast Recovery Rectifier

### Features

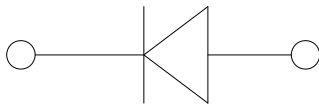
- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Fast reverse recovery time
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

### Typical Applications

For use in high frequency rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, and telecommunication.

### Mechanical Data

**Package:** SMBF  
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free  
**Terminals:** Tin plated leads, solderable per J-STD-020  
Cathode line denotes the cathode end



### Maximum Ratings (T<sub>a</sub>=25 Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GR4MBF
Device marking code			GR4MBF
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	V	1000
Maximum RMS Voltage	V <sub>RMS</sub>	V	700
Maximum DC blocking Voltage	V <sub>DC</sub>	V	1000
Average rectified output current @60Hz half-sine wave, resistance load, TC (Fig.1)	I <sub>O</sub>	A	4.0
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, T <sub>j</sub> =25			120
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, T <sub>j</sub> =25	I <sub>FSM</sub>	A	

Junction temperature	T <sub>j</sub>		-55 ~ +150
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### Electrical Characteristics T<sub>a</sub>=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	GR4MBF
	I <sub>R</sub>	μA	T <sub>j</sub> =25	5.0
			T <sub>j</sub> =125	100j



# GR4MBF

## Thermal Characteristics $T_a=25$ Unless otherwise specified

PARAMETER	SYMBOL	UNIT	GR4MBF
Typical Thermal resistance	$R_{JA}^{(1)}$	/W	60
	$R_{JL}^{(1)}$		20
	$R_{JC}^{(1)}$		15

Note:  
(1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3" x 0.3" (8.0 mm x 8.0 mm) copper pad areas

## Characteristics (Typical)

FIG1  $I_o$  Tc Curve

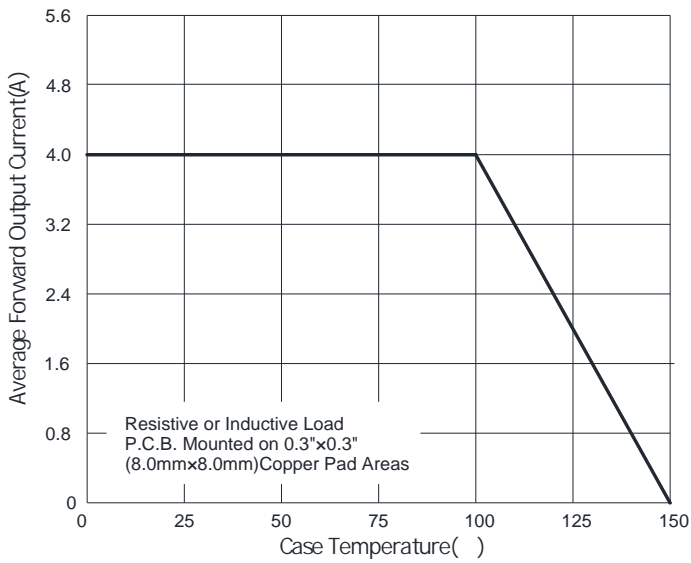


FIG3

Instantaneous Forward Current(A)



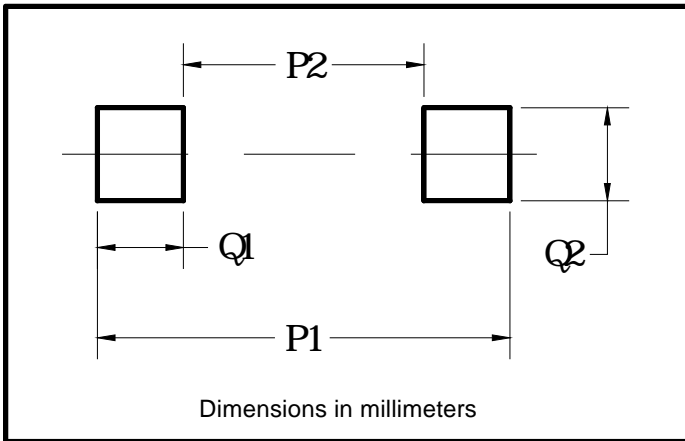
SMBF



Dimensions in millimeters



Suggested pad layout



Dim	Milimeters
P1	6.20
P2	2.40
Q1	1.90
Q2	2.20



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